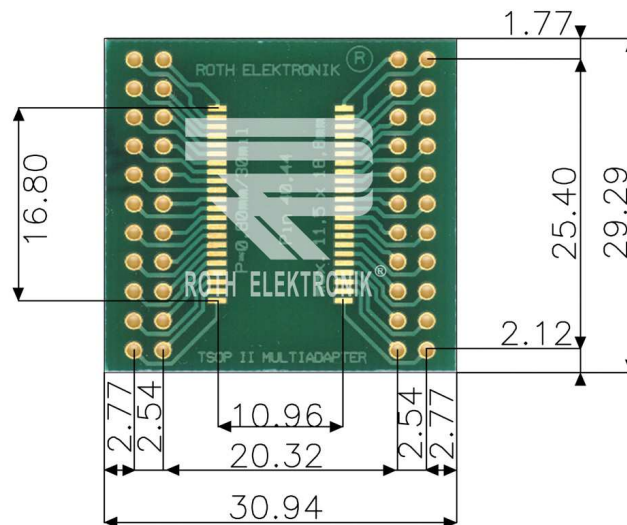




RE900-05

- Epoxy fibre-glass FR4 1.50 mm
 - Double-sided 35 µm Cu
 - Plated through holes (PTH)
 - Surface chem. Ni/Au with solder stop mask
 - Adaption circuit board for TSOP II 40, 44 (0.80 mm)
 - Hole diameter 1.00 mm
 - Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
 - Size 29.29 x 30.94 mm
- Module-No. Typ Pitch Pin Size (mm)

RE900-05 TSOP II 0.800 mm 40, 44 11.50 x 18.80